1981837-1 ✕ OBSOLETE

TE Internal #: 1981837-1

TE Internal Description: SOCKET ASSY LGA1366, 0.38 AU

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IC Socket Type: **LGA 1366**

Connector System: **Board-to-Board**

Number of Positions: **1366**

Contact Mating Area Plating Material Thickness: **[15 µin]**

Centerline (Pitch): **1.02 mm [.04 in]**

Features

Product Type Features

Connector System	Board-to-Board
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Number of Positions	1366
Grid Spacing	1.016 x 1.016 mm[.04 x .04 in]

Body Features

Frame Style	Square

Contact Features

Contact Mating Area Plating Material	Gold
Contact Base Material	Copper Alloy
IC Socket Type	LGA 1366
	15 µin
Contact Current Rating (Max)	.5 A

Mechanical Attachment

PCB Mounting Style	Surface Mount Solder Ball

Connector Mounting Type	Board Mount

Housing Features

Housing Material	High Temperature Thermoplastic
Housing Color	Black
Centerline (Pitch)	1.02 mm[.04 in]

Usage Conditions

Operating Temperature Range	-25 – 100 °C[-13 – 212 °F]

Operation/Application

Circuit Application	Signal

Industry Standards

UL Flammability Rating	UL 94V-0

Packaging Features

Tray Color	Black
Packaging Method	Tray

Other

Socket Connector Comment	Lead-Free Solderball

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JAN 2018 (181) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent

chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Documents

Product Drawings
SOCKET ASSY LGA1366, 0.38 AU

English

CAD Files
3D PDF

3D

Customer View Model

ENG_CVM_CVM_1981837-1_F.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_1981837-1_F.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_1981837-1_F.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages
Sockets_and_Hardware_for_LGA_1366_Processors

English

Product Specifications
Application Specification

English

Instruction Sheets
Instruction Sheet (non U.S.)

English